Tutorial (5/13 Sunday)
3D NAND and Embedded memories
Neuromorphic memories

Invited Speakers (5/14-5/16)
‘3D NAND Flash Memory for Data-intensive Applications’
  S. Inaba, Toshiba
‘Challenges in Automotive Memory Solutions’
  H. Wang, NXP
‘Ferroelectric HfO2 and its Impact on the Memory Landscape’
  S. Müller, FMC
‘DRAM Technology Landscape’
  S. Shiratake, Micron
‘Materials & Processes for Emerging Memory’
  M. Pakala, AMAT
‘High density 3D Cross-point STT-MRAM’
  Y. Huai, Avalanche
‘Phase-Change Memory: Performance, Roles and Challenges’.
  G. Navarro, LETI
‘Cross point Cu ReRAM with BC doped Selector’
  K. Ohba, SONY
‘ReRAM technologies for embedded memory and further applications’
  S. Ito, Panasonic